

Title (en)
Semiconductor power module

Title (de)
Leistungshalbleitermodul

Title (fr)
Module à semi-conducteur de puissance

Publication
EP 0718886 B1 20000830 (DE)

Application
EP 95120111 A 19951219

Priority
DE 4446527 A 19941224

Abstract (en)
[origin: EP0718886A1] The power semiconductor module (1) has a plastics housing (2) with internal struts (7), fitted with a metal or metal/ceramic multi-layer substrate (11) in its base plane. The inwards facing surface of the substrate is provided with the semiconductor components (12) and associated terminals (3), the interior of the housing filled with a soft resin mass (10) overlaid by a hard resin mass (9). The internal struts extend as far as the soft resin mass without direct contact with the substrate, their free ends widened to provide anchoring points, the soft resin mass pref. having a Shore hardness of greater than 20.

IPC 1-7
H01L 25/07; **H01L 23/24**

IPC 8 full level
H01L 23/24 (2006.01); **H01L 25/07** (2006.01)

CPC (source: EP US)
H01L 23/24 (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48472** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

Cited by
EP2892075A3; US9967986B2; US11272625B2; US11672087B2

Designated contracting state (EPC)
DE FR GB IT

DOCDB simple family (publication)
EP 0718886 A1 19960626; **EP 0718886 B1 20000830**; DE 4446527 A1 19960627; DE 59508681 D1 20001005; US 5699232 A 19971216

DOCDB simple family (application)
EP 95120111 A 19951219; DE 4446527 A 19941224; DE 59508681 T 19951219; US 57847795 A 19951226